新世代均匀性改善及镀薄铜填孔电镀铜技术

New Generation Via Filling Acid Copper Plating Technics for Improving Distribution Uniformity and Thinner Copper

MICROFILL™ SFP Acid Copper

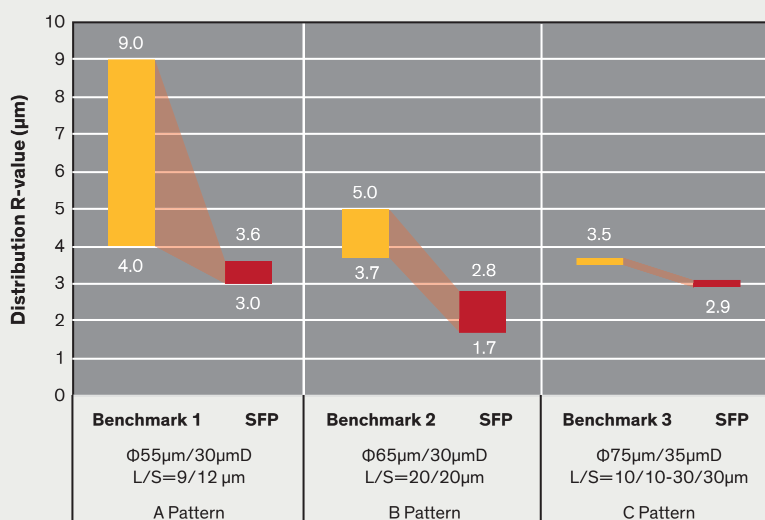
MICROFILL™ SFP Acid Copper is a new generation via-filling acid copper which applies for IC Substrate, and to optimize mSAP yield rate, and enable advanced RDL technics. The outstanding distribution uniformity performance in pattern PCBs enables the industry to achieve higher yield rate, and the thinner platting thickness enhance the technics for advanced fine pitch requirements.

MICROFILL™ SFP Acid Copper为新世代应用于IC Substrate 与优化mSAP良率并实现先进RDL技术之填孔镀铜添加剂。其在图型电镀上优越的均镀能力使得产业能达成更高的产品良率，且其镀薄铜的能力实现了先进细线路的需求。

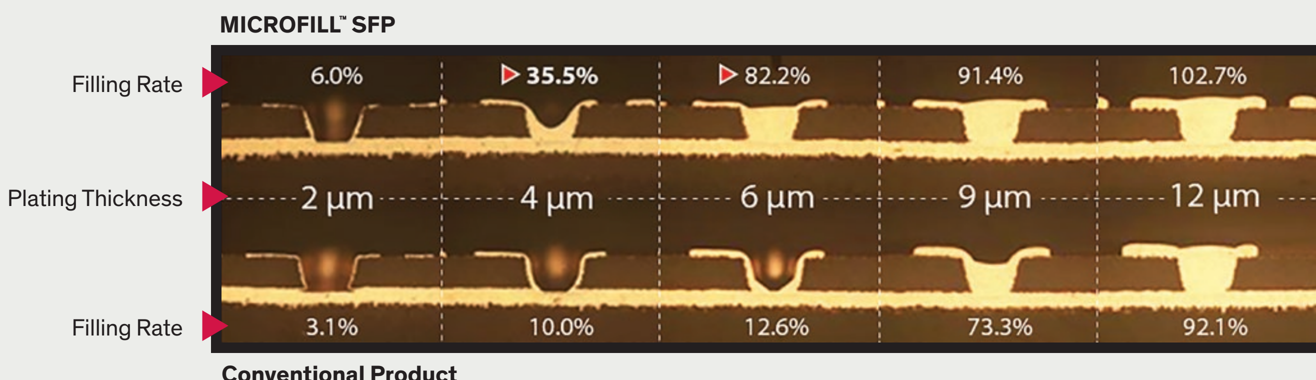
Advantages 优点

- Filling up blind vias in lower plating thickness
  在更低的镀厚下填满盲孔
- Outstanding distribution uniformity
  优越的均镀力
- In higher sulfuric acid (VMS) still works well of blind vias filling
  在高酸(VMS)环境下仍能填满盲孔

- MICROFILL™ SFP provides better pattern plating distribution
  MICROFILL™ SFP 提供更好的图型电镀均匀性



- MICROFILL™ SFP has faster via-filling mechanism (Spec: 60 μmØ / 40 μmd)
  MICROFILL™ SFP能更快达成填孔机制



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